

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5441032

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ASSIGNEE'S ADDRESS previously recorded on Reel 048074 Frame 0471. Assignor(s) hereby confirms the ASSIGNMENT.
CONVEYING PARTY DATA	
Name	Execution Date
JUI-YAO LAI	04/22/2016
YING-YAN CHEN	04/22/2016
YEN-MING CHEN	04/22/2016
SAI-HOOI YEONG	04/22/2016
YUNG-SUNG YEN	04/22/2016
RU-GUN LIU	04/22/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16206803
CORRESPONDENCE DATA	
Fax Number:	(202)756-8087
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-756-8000
Email:	bpugh@mwe.com, WDCIPPTSClerks@mwe.com, ipdocketmwe@mwe.com
Correspondent Name:	MCDERMOTT WILL & EMERY, LLP
Address Line 1:	THE MCDERMOTT BUILDING
Address Line 2:	500 NORTH CAPITOL STREET, N.W.
Address Line 4:	WASHINGTON, D.C. 20001
ATTORNEY DOCKET NUMBER:	095714-0846
NAME OF SUBMITTER:	BRENDA PUGH
SIGNATURE:	/Brenda Pugh/

PATENT

DATE SIGNED:	03/26/2019
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Total Attachments: 6

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Stylesheet Version v1.2

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT														
NATURE OF CONVEYANCE:	Corrective Assignment to correct the EXECUTION DATE OF THE FIFTH AND SIXTH INVENTORS TO READ 04/22/2016 previously recorded on Reel 047645 Frame 0946. Assignor(s) hereby confirms the ASSIGNMENT.														
CONVEYING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>JUI-YAO LAI</td> <td>04/22/2016</td> </tr> <tr> <td>RU-GUN LIU</td> <td>04/22/2016</td> </tr> <tr> <td>SAI-HOOI YEONG</td> <td>04/22/2016</td> </tr> <tr> <td>YEN-MING CHEN</td> <td>04/22/2016</td> </tr> <tr> <td>YUNG-SUNG YEN</td> <td>04/22/2016</td> </tr> <tr> <td>YING-YAN CHEN</td> <td>04/22/2016</td> </tr> </tbody> </table>		Name	Execution Date	JUI-YAO LAI	04/22/2016	RU-GUN LIU	04/22/2016	SAI-HOOI YEONG	04/22/2016	YEN-MING CHEN	04/22/2016	YUNG-SUNG YEN	04/22/2016	YING-YAN CHEN	04/22/2016
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 25%;">Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO. 8 LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSINCHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8 LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK	City:	HSINCHU	State/Country:	TAIWAN	Postal Code:	300				
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Property Type	Number
Application Number:	16206803

CORRESPONDENCE DATA**Fax Number:** (202)756-8087**Phone:** 202-756-8000

Email: bpugh@mwe.com,
ipdocketmwe@mwe.com,
WDCIPPTSClerks@mwe.com

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Address Line 1: THE MCDERMOTT BUILDING**Address Line 2:** 500 NORTH CAPITOL STREET, N.W.**Address Line 4:** WASHINGTON, D.C. 20001**ATTORNEY DOCKET NUMBER:**

095714-0846

NAME OF SUBMITTER:

BRENDA PUGH

Signature:

/Brenda Pugh/

Date:

01/15/2019

Total Attachments: 6

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RECEIPT INFORMATION

EPAS ID: PAT5325382
Receipt Date: 01/15/2019

PATENT

COMBINED DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

I believe I am the original or an original joint inventor of a claimed invention in the application for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE AND A METHOD FOR FABRICATING THE SAME

which application is:

- attached, or
- United States application number or PCT international application number _____ filed on _____.

The above-identified application was made or authorized to be made by me.

In the event that the filing date and/or application number are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the registered practitioners of **McDermott Will & Emery LLP**, associated with the Customer Number **20277**, to insert above the filing date and/or application number of the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign to:

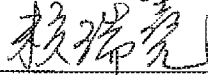
TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.

having an address at No. 8, Li-Hsin Rd. 6, Hsinchu Science-Based Industrial Park, Hsinchu 300, Taiwan (hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in this document.

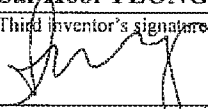
I hereby confirm any prior assignment to Assignee, and to the extent that I have not already done so, agree to assign, and hereby do, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by the undersigned had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

I hereby covenant and agree to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

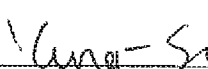
I hereby covenant that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

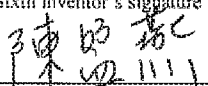
Legal name of first inventor Jui-Yao LAI	
First inventor's signature  Jui-Yao, Lai	Date 2016.4.22

Legal name of second inventor, if any RU-GUN LIU	
Second inventor's signature Ru-Gun Liu	Date 2016.4.27

Legal name of third inventor, if any Sai-Hooi YEONG	
Third inventor's signature  楊世偉	Date 2016/4/22

Legal name of fourth inventor, if any Yen-Ming CHEN	
Fourth inventor's signature Yen-Ming Chen	Date 2016/4/22

Legal name of fifth inventor, if any Yung-Sung YEN	
Fifth inventor's signature  Yung-Sung Yen	Date 2016.4.22

Legal name of sixth inventor, if any Ying-Yan CHEN	
Sixth inventor's signature  陳妍	Date 2016.4.22